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2877

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Peter G. Borden; Jiping Li; Jon Madsen
Assignee: Boxer Cross
Title: Calibration As Well As Measurement On The Same Workpiece During Fabrication
Serial No.: 09/974,571 Filing Date: Oct. 9, 2001
Examiner: Unknown Group Art Unit: 2877
Docket No.: BOX013 US Confirmation No: 1003

Santa Clara, California
January 05, 2004

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR §1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, §1.97 and §1.98, the Applicants submit for consideration in the above-identified patent application the document listed on the accompanying Form PTO-1449. Copies of references numbered 52-86 are submitted herewith. The Examiner is requested to make these documents of record. The remaining references are not attached hereto, because these references are issued patents or publications which are readily available in the U.S. Patent and Trademark Office.

In addition, Applicants submit, for the Examiner's consideration, the prosecution histories of the following co-owned applications/patents, cited by serial number, first named inventor and filing date. The Applicants presume that the Examiner has access to and will review the applications/patents and the files thereof for any office actions, amendments or other materials that may be relevant to the patentability of the claims of the present application.

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Citation of these prosecution histories (including the arguments against patentability advanced by Examiners in their respective Office Actions and the Applicants' arguments in the corresponding Amendments) is in accordance with the recent case DAYCO PRODUCTS, INC. v. TOTAL CONTAINMENT, INC., 02-1497, decided May 23, 2003 by the Court of Appeals for the Federal Circuit. The Examiner is presumed to be knowledgeable about the current case law, including the above-mentioned Dayco case. However, if the Examiner needs a copy of the Dayco case, please call the undersigned.

For any such U.S. patent application(s) that are currently pending, the Applicants further presume that the Examiner will consider any future office actions, amendments or other materials in the file thereof that may be relevant to the patentability of the claims herein. **If the Applicants' understanding in this regard is not correct, please notify the undersigned so that copies of any such documents can be submitted to the Examiner.**

	Serial No.:	First Named Inventor	Date:
1.	10/090,316	Peter G. Borden	03/01/2002
2.	10/090,287	Peter G. Borden	03/01/2002
3.	09/521,232	Peter G. Borden	03/08/2000
4.	10/090,262	Peter G. Borden	03/01/2002
5.	09/788,273	Jiping Li	02/16/2001
6.	10/722,724	Peter G. Borden	11/25/2003
7.	09/095,805	Peter G. Borden	06/10/1998
8.	09/095,804	Peter G. Borden	06/10/1998
9.	09/544,280	Peter G. Borden	04/06/2000
10.	10/269,619	Peter G. Borden	10/11/2002
11.	10/253,119	Peter G. Borden	09/23/2002
12.	10/253,121	Peter G. Borden	09/23/2002
13.	09/274,821	Peter G. Borden	03/22/1999
14.	09/935,128	Peter G. Borden	08/21/2001
15.	09/994,441	Peter G. Borden	11/26/2001
16.	10/223,952	Peter G. Borden	08/19/2002
17.	09/799,481	Peter G. Borden	03/05/2001

This Information Disclosure Statement is submitted pursuant to 37 CFR §1.97(b) as it within three months of the filing date of a national application other than a continued prosecution application and/or before the mailing of a first Office Action on the merits. Accordingly, no fee is required.

Applicants would appreciate the Examiner initialing and returning the Form PTO-1449, indicating that the information has been considered and made of record herein.

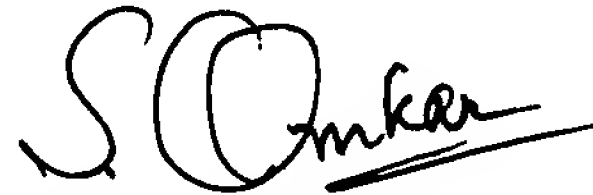
The information contained in this Information Disclosure Statement is to the best of my knowledge and is not to be construed as a representation that: (i) a complete search has

been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the above information constitutes prior art to the subject invention.

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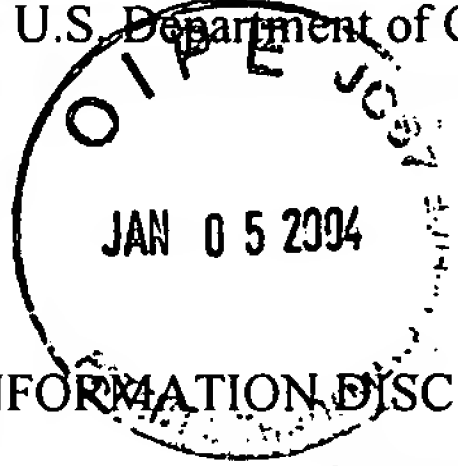
Respectfully submitted,



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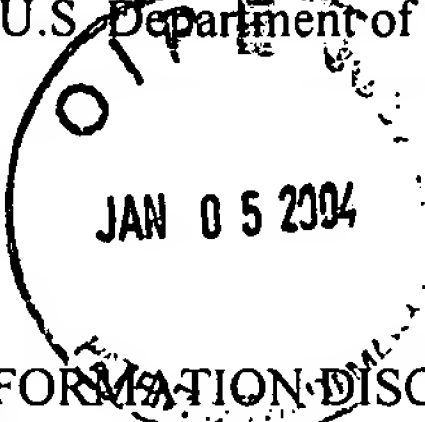
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U.S. Department of Commerce, Patent and Trademark Office  INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/974,571
	Filing Date:	October 9, 2001
	First Named Inventor:	Peter G. Borden
	Group Art Unit:	2877
	Examiner Name:	Unknown
	Confirmation No.:	1003
	Attorney Docket No.:	BOX013 US

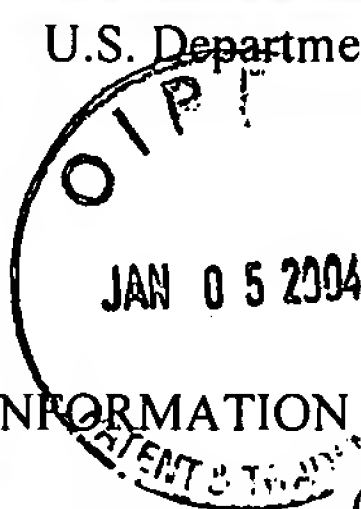
U.S. Patent Documents							
*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
	1.	4,273,421	6/16/81	Gurtler	356	432	
	2.	4,854,710	8/8/89	Opsal et al.	356	432	
	3.	4,211,488	7/8/80	Kleinknecht	356	433	
	4.	5,379,109	1/3/95	Gaskill et al.	356	445	
	5.	6,489,801	12/3/02	Borden et al.	324	766	
	6.	5,966,019	10/12/99	Borden	324	752	
	7.	5,377,006	12/27/94	Nakata	356	349	
	8.	5,706,094	1/6/98	Maris	356	432	
	9.	6,118,533	9/12/00	Banet et al.	356	345	
	10.	6,323,951	11/27/01	Borden et al.	356	502	
	1.	6,426,644	7/30/02	Borden et al.	324	766	
	12.	4,952,063	8/27/90	Opsal et al.	356	432	
	13.	5,042,952	827/1991	Opsal et al.	356	432	
	14.	5,159,412	10/27/92	Willenborg et al.	356	445	
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	19.	4,579,463	4/1/86	Rosencwaig et al.	374	57	
	19.	4,632,561	12/30/86	Rosencwaig et al.	356	432	
	20.	4,636,088	1/13/87	Rosencwaig et al.	374	5	
	21.	4,750,822	6/14/88	Rosencwaig et al.	324	445	
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	24.	6,483,594	11/19/02	Borden et al.	356	502	
	25.	5,652,716	7/29/97	Battersby	703	13	

Examiner:	Date Considered:
* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.	

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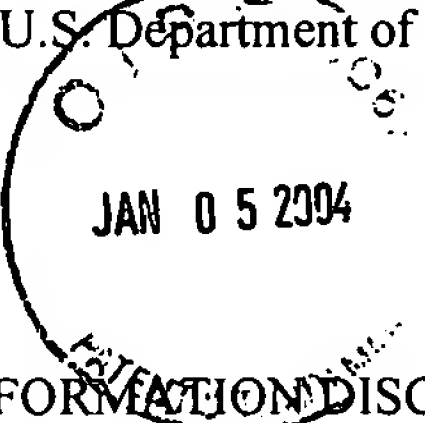
	26	5,761,082	6/2/98	Miura-Mattausch	703	14	
	27	4,996,659	2/26/91	Yamaguchi et al.	714	736	
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	29	6,054,868	4/25/00	Borden et al.	324	752	
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	38	4,201,087	5/6/80	Akita et al.	73	339	
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	40	6,486,965	11/26/02	Kim	356	626	
	41	5,741,614	4/21/98	McCoy et al.	430	30	
	42	6,327,035	12/4/01	Li et al.	356	432	
	43	5,454,004	9/26/95	Leger	372	99	
	44	6,281,027	9/28/01	Wei et al.	438	14	
	45	4,521,118	06/00/85	Rosencwaig	374	5	
	46	5,074 669	12/1/91	Opsal	356	447	
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	48	5,657,754	8/19/97	Rosencwaig	128	633	
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	50	4,552,510	6/11/85	Rosencwaig	374	7	
	51	4,571,685	02/18/86	Kamoshida	364	468	

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Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	52.	99/94880	12/16/1999	PCT	G01R	31/26		
	53.	00/07357	3/20/2000	PCT	G01L	21/17		
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
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	55.	Rosencwaig, "Thermal-Wave Imaging", SCIENCE, Volume 218, No. 4569, Oct. 1982, pp.223-228						
	56.	Opsal et al. "Thermal-Wave Detection and Thin-Film Thickness Measurements with Laser Beam Deflection", Applied Optics, Vol. 22, No. 20, Oct. 1983, pp. 3169-3176						
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	59.	W. L. Smith et al. "Ion Implant Monitoring With Thermal Wave Technology," Nuclear Instruments and Methods Physics Research, B21, (1987), 537-541.						
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	65.	A. Rosencwaig, "Thermal Wave Measurement of Thin-Film Thickness", 1986 American Chemical Society, pp.182-191						
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72	A. Rosencwaig, "Thermal Wave Monitoring and Imaging of Electronic Materials and Devices", pp 73-109
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76	W. Lee Smith, "Nondestructive Thermal Wave Imaging of Voids & Microcracks in Aluminum Metallization", 1989 WLR Final Report, pp 55-68
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83	R. L. Thomas et al., "Thermal Wave Imaging For Nondestructive Evaluation" 1982 Ultrasonic Symposium, pp 586-590
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